

Listing of Claims:

1. (original) A pressure piece for effecting pressure contact within a power semiconductor module, the module includes a housing, at least one electrically insulating substrate having an insulating body with a plurality of metal connection tracks located therein and insulated from one another, at least one power semiconductor component located on and electrically connected to the connection tracks and at least partially resilient connection leads, for electrically connecting the connection tracks to a printed circuit board disposed outside the housing,

wherein the pressure piece is dimensionally stable and includes a plurality of pressure elements disposed on a first primary face of the pressure piece facing the printed circuit board, and the pressure elements space the primary face from the printed circuit board.

2. (currently amended) The pressure piece of claim 1, wherein ~~the~~ each pressure piece element has at least one edge, a second primary face and at least one opening connecting the first and second primary faces, and

the pressure elements are disposed such that a fluid may flow between the at least one edge and the at least one opening.

3. (cancelled)

4. (original) The pressure piece of claim 1, wherein the pressure piece comprises an electrically insulating, dimensionally stable, plastic.

5. (original) The pressure piece of claim 1, wherein the pressure piece comprises a composite of an electrically insulating plastic and a metal core.

6. (cancelled)

7. (original) The pressure piece of claim 1, wherein the plurality of pressure elements includes at least one prong.

8. (currently amended) The pressure piece of claim 6 11, wherein the plurality of pressure elements includes at least two ribs which form a frame.

9. (currently amended) The pressure piece of claim 6 11, wherein the at least one rib has at least one notch to permit fluid to flow therethrough.

10. (New) A pressure piece for effecting pressure contact within a power semiconductor module, the module includes a housing, at least one electrically insulating substrate having an insulating body with a plurality of metal connection tracks located therein and insulated from one another, at least one power semiconductor component located on and electrically connected to the connection tracks and at least partially resilient connection leads, for electrically connecting the connection tracks to a printed circuit board disposed outside the housing;

wherein the pressure piece is dimensionally stable and includes a plurality of pressure elements disposed on a first primary face of the pressure piece facing the printed circuit board, and the pressure elements space the primary face from the printed circuit board; and

wherein the pressure piece has at least one electrically insulated sheath for receiving a screw connection.

11. (New) A pressure piece for effecting pressure contact within a power semiconductor module, the module includes a housing, at least one electrically insulating substrate having an insulating body with a plurality of metal connection tracks located therein and insulated from one another, at least one power semiconductor component located on and electrically connected to the connection tracks and at least partially resilient connection leads, for electrically connecting the connection tracks to a printed circuit board disposed outside the housing;

wherein the pressure piece is dimensionally stable and includes a plurality of pressure elements disposed on a first primary face of the pressure piece facing the printed circuit board, and the pressure elements space the primary face from the printed circuit board; and

wherein the plurality of pressure elements includes at least one rib.